Material Processing and Assembly of CPMM

To protect the memory module of electronic device from high impact shock, high flame heat flux and moderate environmental heat flux, there are numerous methods exist. Generally, the principal for selection of the materials as widely accepted for such applications are low density and thermal conductivity, high specific heat etc.

DMSRDE, Kanpur has developed a process using four layered functionally separated non-metallic materials to prepare a protective enclosures to achieve high impact shock absorption characteristic and thermal shielding to protect memory module of electronic devices encapsulated either in a titanium alloy enclosure, which may be used in aircrafts, helicopters etc. In this DMSRDE, Kanpur has developed a method for processing of these quality materials and their lay-up to achieve optimum performance. The data recorded in memory module of electronic device which is kept inside the series of protective enclosures should be retrievable 100% even after subjected to tests conducted as per TSO-C-124a.